

## ABSTRACT

A first container member (9, 109, 212) mounting an electronic device (71, 171, 261) thereon and a second container member (2, 102, 202) are bonded with an adhesive 5 (3, 103) or a metal layer (103, 251). Thus an inner space (90, 190, 211) is formed and the electronic device can be closed in the inner space at a low temperature. In the case the adhesive is used, an exposed surface of the adhesive is coated with a metal film (4) to improve the 10 closeness of the inner space. Further, an electronic device (261, 272) may be mounted on the second container member so as to increase the electronic device arrangement density in a packaged electronic device.